

TRADEMARK ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT
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NATURE OF CONVEYANCE:	Intellectual Property Security Agreement
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CONVEYING PARTY DATA

Name	Formerly	Execution Date	Entity Type
Strasbaugh		08/07/2005	CORPORATION: CALIFORNIA

RECEIVING PARTY DATA

Name:	Agility Capital, LLC
Street Address:	226 E. Canon Perdido Street, Suite F
City:	Santa Barbara
State/Country:	CALIFORNIA
Postal Code:	93101
Entity Type:	limited liability company: CALIFORNIA

PROPERTY NUMBERS Total: 8

Property Type	Number	Word Mark
Registration Number:	2880241	NOVATION
Registration Number:	2880242	NHANCE
Registration Number:	2882921	NTELLECT
Registration Number:	2898049	NCOMPASS
Registration Number:	2753644	SMARTPAD
Registration Number:	2139643	SYMPHONY CMP
Serial Number:	78133081	NVISION
Serial Number:	78133120	NFINITY

CORRESPONDENCE DATA

Fax Number: (650)849-7400
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
 Phone: 6508435381
 Email: dsanchezbentz@cooley.com
 Correspondent Name: Diana Sanchez Bentz
 Address Line 1: Cooley Godward LLP, 5 Palo Alto Square

CH \$215.00 2880241

Address Line 2: 3000 El Camino Real
Address Line 4: Palo Alto, CALIFORNIA 94306

NAME OF SUBMITTER:	Diana Sanchez Bentz
Signature:	/dsb4232/
Date:	09/07/2005

Total Attachments: 5
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INTELLECTUAL PROPERTY SECURITY AGREEMENT

THIS INTELLECTUAL PROPERTY SECURITY AGREEMENT is entered into as of August 7, 2005 by and between **AGILITY CAPITAL, LLC ("Lender")** and **STRASBAUGH**, a California corporation ("**Grantor**").

RECITALS

Lender has agreed to make certain advances of money and to extend certain financial accommodation to Grantor (the "**Loans**") in the amounts and manner set forth in that certain Loan Agreement by and between Lender and Grantor (as amended from time to time, the "**Loan Agreement**") dated of even date herewith. Capitalized terms used herein have the meaning assigned in the Loan Agreement. Lender is willing to make the credit extensions to Grantor, but only upon the condition, among others, that Grantor shall grant to Lender a security interest in all of Grantor's right title, and interest in, to and under all of the Collateral whether presently existing or hereafter acquired

NOW, THEREFORE, Grantor agrees as follows:

AGREEMENT

To secure performance of Grantor's obligations under the Loan Agreement, Grantor grants to Lender a security interest in all of Grantor's right, title and interest in Grantor's intellectual property (including without limitation those Copyrights, Patents and Trademarks listed on Schedules A, B and C hereto), including without limitation all proceeds thereof (such as, by way of example but not by way of limitation, license royalties and proceeds of infringement suits). This security interest is granted in conjunction with the security interest granted to Lender under the Loan Agreement. Each right, power and remedy of Lender provided for herein shall not preclude the simultaneous or later exercise by Lender of any or all other rights, powers or remedies.

IN WITNESS WHEREOF, the parties have caused this Intellectual Property Security Agreement to be duly executed as of the first date written above.

Address of Borrower:

825 Buckley Road
San Luis Obispo, CA 93401
Attn: Chuck Shillings, Chief Executive Officer

STRASBAUGH

By: 

Title: CHIEF FINANCIAL OFFICER

Address of Lender:

226 E. Canon Perdido Street, Suite F
Santa Barbara, CA 93101

AGILITY CAPITAL, LLC

By: 

Title: Chief Credit officer

EXHIBIT A

Copyrights

Title	Registration Number	Registration Date
NONE		

EXHIBIT B

Patents/Patent Applications

<u>TITLE</u>	<u>SERIAL/ PATENT NO.</u>	<u>APPLICATION/ ISSUE DATE</u>
WAFER-HANDLING APPARATUS HAVING A RESILIENT MEMBRANE WHICH HOLDS WATER WHEN A VACUUM IS APPLIED	5423716	06/13/1995
WAFER CARRIER FOR FILM PLANARIZATION	5449316	09/12/1995
APPARATUS FOR SENSING THE PRESENCE OF A WAFER	5961169	10/05/1999
GRINDING PROCESS AND APPARATUS FOR PLANARIZING SAWED WAFERS	5964646	10/12/1999
CHEMICAL MECHANICAL POLISHING APPARATUS AND METHOD	6045716	04/04/2000
LIFTING AND RINSING A WAFER	6102057	08/15/2000
ACCURATE POSITIONING OF A WAFER	6131589	10/17/2000
SLURRY PUMP CONTROL SYSTEM	6183341	02/06/2001
PAD QUICK RELEASE DEVICE FOR CHEMICAL MECHANICAL POLISHING	6227956	05/08/2001
APPARATUS AND METHOD FOR RELIABLY RELEASING WET, THIN WAFERS	6254155	07/03/2001
SENSING THE PRESENCE OF A WAFER	6267642	07/31/2001
NON-CONTACTING SUPPORT FOR A WAFER	6283827	09/04/2001
MULTI-PAD APPARATUS FOR CHEMICAL MECHANICAL PLANARIZATION	6346036	02/12/2002
PARALLEL ALIGNMENT METHOD AND APPARATUS FOR CHEMICAL MECHANICAL POLISHING	6354926	03/12/2002
METHOD AND APPARATUS FOR CHEMICAL MECHANICAL POLISHING	6361647	03/26/2002
WAFER SUPPORT FOR CHEMICAL MECHANICAL PLANARIZATION	6379235	04/30/2002
PAD TRANSFER APPARATUS FOR CHEMICAL MECHANICAL PLANARIZATION	6450860	09/17/2002
PAD QUICK RELEASE DEVICE FOR CHEMICAL MECHANICAL PLANARIZATION	6464574	10/15/2002
METHOD FOR CHEMICAL MECHANICAL POLISHING	6495463	12/17/2002
SPHERICAL DRIVE ASSEMBLY FOR CHEMICAL MECHANICAL PLANARIZATION	6511368	01/28/2003
POLISHING CHEMICAL DELIVERY FOR SMALL HEAD CHEMICAL MECHANICAL PLANARIZATION	6514121	02/04/2003
MULTI-ACTION CHEMICAL MECHANICAL PLANARIZATION DEVICE AND METHOD	6514129	02/04/2003
SHAPING POLISHING PAD FOR SMALL HEAD CHEMICAL MECHANICAL PLANARIZATION	6517419	02/11/2003
HIGH PLANARITY CHEMICAL MECHANICAL PLANARIZATION	6520843	02/18/2003
PAD RETRIEVAL APPARATUS FOR CHEMICAL MECHANICAL PLANARIZATION	6527621	03/04/2003
SUBAPERATURE CHEMICAL MECHANICAL PLANARIZATION WITH POLISHING PAD CONDITIONING	6547651	04/15/2003
HARD POLISHING PAD FOR CHEMICAL MECHANICAL PLANARIZATION	6551179	04/22/2003
PAD SUPPORT APPARATUS FOR CHEMICAL MECHANICAL PLANARIZATION	6602121	08/05/2003

<u>TITLE</u>	<u>SERIAL/ PATENT NO.</u>	<u>APPLICATION/ ISSUE DATE</u>
FEATURE HEIGHT MEASUREMENT DURING CMP	6629874	10/07/2003
COMBINED CHEMICAL MECHANICAL PLANARIZATION AND CLEANING	6692339	02/17/2004
MODULAR METHOD FOR CHEMICAL MECHANICAL PLANARIZATION	6855030	02/15/2005
RETAINING RING FOR WAFER CARRIERS	6869348	03/22/2005
DEVICE FOR SUPPORTING THIN SEMICONDUCTOR WAFERS	6885206	04/26/2005
OPTICAL VIEW PORT FOR CHEMICAL MECHANICAL PLANARIZATION ENDPOINT DETECTION	6146242	11/14/2000
LIFTING AND RINSING A WAFER	6505635	01/14/2003
METHOD FOR MAKING A POLISHING PAD WITH BUILT-IN OPTICAL SENSOR	6696005	02/24/2004
POLISHING PAD WITH OPTICAL SENSOR	6726528	04/27/2004
POLISHING PAD WITH BUILT-IN OPTICAL SENSOR	6739945	05/25/2004
METHOD OF SPIN ETCHING WAFERS WITH AN ALKALI SOLUTION	6743722	06/01/2004
POLISHING PAD SENSOR ASSEMBLY WITH A DAMPING PAD	6884150	04/26/2005
POLISHING PAD WITH BUILT-IN OPTICAL SENSOR	6485354	11/26/2002
METHOD OF PREPARING WHOLE SEMICONDUCTOR WAFER FOR ANALYSIS	6921719	07/26/2005
ACCURATE POSITIONING OF A WAFER	6405740	06/18/2002
OPTICAL VIEW PORT FOR CHEMICAL MECHANICAL PLANARIZATION ENDPOINT DETECTION	6488568	12/03/2002
ENDPOINT DETECTION SYSTEM FOR WAFER POLISHING	6695681	02/24/2004
METHOD FOR APPLYING AN INSERT OR TAPE TO CHUCKS OR WAFER CARRIERS USED FOR GRINDING, POLISHING, OR PLANARIZING WAFERS	6638389	10/28/2003
LAP SHAPING MACHINE WITH OSCILLATABLE POINT CUTTER AND SELECTIVELY ROTATABLE OR OSCILLATABLE LAP	4380412	04/19/1983
LAP MILLING MACHINE	3986433	10/19/1976
FLUID RESPONSIVE, LEVERAGE OPERATED CHUCK	3962832	06/15/1976
PROTECTION OF WORK PIECE DURING SURFACE PROCESSING	10249433	04/08/2003
WAFER CARRIER PIVOT MECHANISM	10425896	04/28/2003
DEVICES AND METHODS FOR OPTICAL ENDPOINT DETECTION DURING SEMICONDUCTOR WAFER POLISHING	10754360	01/08/2004
METHOD OF BACKGRINDING WAFERS WHILE LEAVING BACKGRINDING TAPE ON A CHUCK	10717032	11/18/2003
SUPPORT FOR THIN WAFERS	10365081	02/11/2003
SLURRY PUMP CONTROL SYSTEM	10626490	07/22/2003
METHOD OF PREPARING WHOLE SEMICONDUCTOR WAFER FOR ANALYSIS	10065589	10/31/2002
MODULAR METHOD FOR CHEMICAL MECHANICAL PLANARIZATION	10327712	12/19/2002
POLISHING PAD WITH OPTICAL SENSOR	10146494	05/14/2002
POLISHING PAD WITH BUILT-IN OPTICAL SENSOR	10145332	05/14/2002
SUBAPERTURE CHEMICAL MECHANICAL PLANARIZATION WITH POLISHING PAD CONDITIONING	10374494	02/25/2003
METHOD OF BACKGRINDING WAFERS WHILE LEAVING BACKGRINDING TAPE ON A CHUCK	10313576	12/10/2002
ENDPOINT DETECTION SYSTEM FOR WAFER POLISHING	10303621	12/25/2002

EXHIBIT C

Trademarks/Trademark Applications

<u>Description</u>	<u>Registration/ Serial Number</u>	<u>Registration/ Application Date</u>
NOVATION	2880241	08/31/2004
NHANCE	2880242	08/31/2004
NTELLECT	2882921	09/07/2004
NCOMPASS	2898049	10/26/2004
SMARTPAD	2753644	08/19/2003
SYMPHONY CMP	2139643	02/19/1998
NVISION	78133081	06/04/2002
NFINITY	78133120	06/04/2002